

a first moving means for imparting relative motion in a direction horizontal to the polishing surface of said polishing tool between said dressing tool and said polishing tool;

a second moving means for moving said dressing tool in a direction vertical to the polishing surface of said polishing tool; and

a control means for permitting to execute movement caused by said first moving means while controlling a position of said second moving means.

5. (Amended) The polishing apparatus according to claim 1, wherein said control means comprises a detection means for detecting contact of said polishing tool with said dressing tool and controls to stop said second moving means on the basis of the detection of contact between said polishing tool and said dressing tool by said detection means.

10. (Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion and a polishing tool to polish the surface of said workpiece by the polishing surface of said polishing tool, comprising:

a dressing tool for forming a surface roughness on the polishing surface of said polishing tool; and

a means for inhibiting movement of a grindstone in a direction vertical to the polishing surface of said polishing tool.

11. (Amended) A method for manufacturing a semiconductor for effecting polishing-processing while pressing the thin film surface adhered to the surface of a

semiconductor substrate formed with an irregularity pattern to the polishing surface of a polishing tool for relative motion comprising:

forming a surface roughness with a dressing tool on the polishing surface of said polishing tool, during a period between polishing processing or during the polishing process, while controlling movement of said dressing tool in a vertical direction with respect to said polishing surface.

REMARKS

Claims 1-11 are pending. By this amendment, claims 1, 5, 10 and 11 are amended.

The Office Action objects to claim 11. Claim 11 has been amended. Accordingly, Applicant's request withdrawal of the objection to claim 11.

The Office Action rejects claims 1-9 and 11 under 25 USC § 112, second paragraph. This rejection is respectfully traversed.

Regarding claim 1, the claim has been amended to obviate concerns raised in the Office Action. Furthermore, the direction mentioned in the claim is recited as a direction vertical to the polishing surface of the polishing tool, and therefore is definite under 35 USC § 112.

The Office Action rejects 1-10 under 35 USC § 102(b) over McHugh, et al. (U.S. Patent 5,647,788). This rejection is respectfully traversed.

If McHugh, et al., the grinding wheels G grind a diesel crank shaft. The dressing tool 3 moves in the direction vertical to circumferences of the grinding wheels G in order to dress the wheels G. Also, dressing tool 3 moves in the direction parallel to an axis of a shaft of the grinding wheels G. The circumference of the grinding wheel G is a polishing surface, round, and